MAY 2 4 2004 &

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Bayot

Docket No:

TI-33474

Serial No:

09/963,493

Examiner:

Coleman, William

mey

Filed:

9/27/2001

Art Unit:

2823

For:

METHODS OF AND APPARATUS FOR MANUFACTURING BALL GRID

ARRAY SEMICONDUCTOR DEVICE PACKAGES

APPEAL BRIEF PURSUANT TO 1.192(c)

Assistant Commissioner for Patents Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A) I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

The following Appeal Brief is respectfully submitted in triplicate and in connection with the above identified application in response to the Final Office Action mailed October 16, 2003.

REAL PARTY IN INTEREST

The real party in interest is Texas Instruments Incorporated.

RELATED APPEALS AND INTERFERENCES

Appellants legal representative knows of no appeals or interferences which will be directly affected or have a bearing on the Board's decision.

06/07/2004 CPARIS

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